

International Engineering Consortium

DesignCon 2008

February 4-7, 2008
Santa Clara, California, USA

Volume 1 of 3

Printed from e-media with permission by:

Curran Associates, Inc.
57 Morehouse Lane
Red Hook, NY 12571
www.proceedings.com

ISBN: 978-1-60560-345-2

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International Engineering Consortium

300 W. Adams Street
Suite 1210
Chicago, IL 60606-5114
Phone: +1-312-559-4100
Fax: +1-312-559-4111

info@iec.org

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